

CLAIMS

What is claimed is:

1 1. An interposer to couple a die to a substrate and comprising:
2 a capacitor having first and second terminals;
3 a first plurality of lands on a first surface thereof, including a first land
4 coupled to the first terminal and a second land coupled to the second terminal; and
5 a second plurality of lands on a second surface thereof, including a third land
6 coupled to the first terminal and a fourth land coupled to the second terminal.

1 2. The interposer recited in claim 1 wherein the first and second lands are
2 positioned to be coupled to corresponding power supply nodes of the die, and
3 wherein the third and fourth nodes are positioned to be coupled to corresponding
4 power supply nodes of the substrate.

1 3. The interposer recited in claim 1 wherein the first and second lands are
2 coupled to the first and second terminals, respectively, of the capacitor by a
3 conductive path that comprises at least one via, and wherein the third and fourth
4 lands are coupled to the first and second terminals, respectively, of the capacitor by
5 a conductive path that comprises at least one additional via.

1 4. The interposer recited in claim 3 wherein the at least one via and the at least
2 one additional via are located at an interior region of the interposer.

1 5. The interposer recited in claim 3 wherein the at least one via and the at least
2 one additional via are located at a peripheral region of the interposer.

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1 6. The interposer recited in claim 1 wherein the capacitor comprises at least one
2 high permittivity layer.

1 7. The interposer recited in claim 1 wherein the capacitor comprises a plurality
2 of high permittivity layers.

1 8. The interposer recited in claim 7 wherein the capacitor comprises a plurality
2 of conductive layers interleaved with the high permittivity layers, such that
3 alternating conductive layers are coupled to the first and second lands, respectively.

1 9. The interposer recited in claim 1 wherein the capacitor comprises at least one
2 embedded discrete capacitor.

1 10. The interposer recited in claim 1 wherein the first plurality of lands
2 comprises a fifth land positioned to be coupled to a corresponding signal node of the
3 die, and wherein the second plurality of lands comprises a sixth land positioned to
4 be coupled to a corresponding signal node of the substrate.

1 11. The interposer recited in claim 10 wherein the fifth and sixth lands are
2 coupled by a conductive path that comprises at least one via.

1 12. An electronic assembly comprising:
2 a die comprising first and second power supply nodes;
3 a substrate having third and fourth power supply nodes; and
4 an interposer coupling the die to the substrate and comprising:
5 a capacitor having first and second terminals;
6 a first plurality of lands on a first surface thereof, including a first
7 land coupled to the first power supply node and the first terminal, and further

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10 a second plurality of lands on a second surface thereof, including a
11 third land coupled to the third power supply node and the first terminal, and further
12 including a fourth land coupled to the fourth power supply node and the second
13 terminal.

1 17. The electronic system recited in claim 16 wherein the capacitor comprises a
2 plurality of high permittivity layers.

1 18. The electronic system recited in claim 17 wherein the capacitor comprises a
2 plurality of conductive layers interleaved with the high permittivity layers, such that
3 alternating conductive layers are coupled to the first and second lands, respectively.

1 19. The electronic system recited in claim 16 wherein the capacitor comprises at
2 least one embedded discrete capacitor.

1 20. A data processing system comprising:
2 a bus coupling components in the data processing system;
3 a display coupled to the bus;
4 external memory coupled to the bus; and
5 a processor coupled to the bus and comprising an electronic assembly
6 including:
7 a die comprising first and second power supply nodes;
8 a substrate having third and fourth power supply nodes; and
9 an interposer coupling the die to the substrate and comprising:
10 a capacitor having first and second terminals;
11 a first plurality of lands on a first surface thereof, including a
12 first land coupled to the first power supply node and the first terminal, and further

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13 including a second land coupled to the second power supply node and the second
14 terminal; and
15 a second plurality of lands on a second surface thereof,
16 including a third land coupled to the third power supply node and the first terminal,
17 and further including a fourth land coupled to the fourth power supply node and the
18 second terminal.

1 21. The data processing system recited in claim 20 wherein the capacitor
2 comprises a plurality of high permittivity layers.

1 22. The data processing system recited in claim 21 wherein the capacitor
2 comprises a plurality of conductive layers interleaved with the high permittivity
3 layers, such that alternating conductive layers are coupled to the first and second
4 lands, respectively.

1 23. A method for making an interposer to couple a die to a substrate, the
2 method comprising:
3 forming within a multilayer ceramic structure at least one capacitor having
4 first and second terminals;
5 forming in the structure first and second power supply nodes;
6 forming a first plurality of lands on a first surface of the structure, including
7 a first land coupled to the first terminal and to the first power supply node, and a
8 second land coupled to the second terminal and to the second power supply node,
9 wherein the first and second lands are positioned to be coupled to first and second
10 power supply nodes of the die; and
11 forming a second plurality of lands on a second surface of the structure,
12 including a third land coupled to the first terminal and to the first power supply
13 node, and a fourth land coupled to the second terminal and to the second power

14 supply node, wherein the third and fourth lands are positioned to be coupled to first
15 and second power supply nodes of the substrate.

1 24. The method recited in claim 23 wherein the at least one capacitor is formed
2 of a plurality of high permittivity layers.

1 25. The method recited in claim 24 wherein the at least one capacitor is formed
2 of a plurality of conductive layers interleaved with the high permittivity layers, such
3 that alternating conductive layers are coupled to the first and second lands,
4 respectively.

1 26. The method recited in claim 23 wherein the at least one capacitor is formed
2 of at least one embedded discrete capacitor.

1 27. A method of making an electronic assembly comprising:
2 providing a die having first and second power supply nodes;
3 providing an interposer comprising:
4 at least one capacitor having first and second terminals; and
5 a first plurality of lands on a first surface thereof including a first
6 land coupled to the first terminal, and a second land coupled to the second terminal;
7 and
8 a second plurality of lands on a second surface thereof including a
9 third land coupled to the first terminal, and a fourth land coupled to the second
10 terminal;
11 providing a substrate comprising third and fourth power supply nodes;
12 coupling the first and second lands to the first and second power supply
13 nodes; and

14 coupling the third and fourth lands to the third and fourth power supply
15 nodes.

1 28. The method recited in claim 27 wherein the at least one capacitor is formed
2 of a plurality of high permittivity layers.

1 29. The method recited in claim 28 wherein the at least one capacitor is formed
2 of a plurality of conductive layers interleaved with the high permittivity layers, such
3 that alternating conductive layers are coupled to the first and second lands,
4 respectively.

1 30. The method recited in claim 27 wherein the at least one capacitor is formed
2 of at least one embedded discrete capacitor.

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